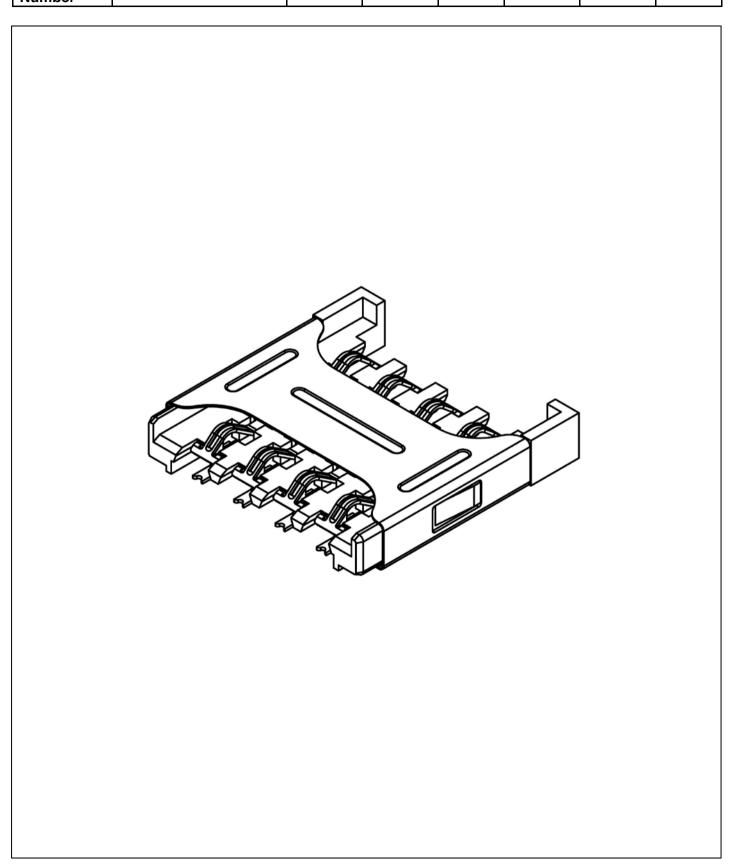
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#### 1.0 SCOPE.

This specification covers performance, tests and quality requirements for the Micro SIM Card Connector SIM7050 (Retainer Type, 6 & 8Pin, SMT, 2.45mm Profile).

#### 2.0 PRODUCT NAME AND PART NUMBER.

Micro SIM Card Connector, 6 & 8 Pin, Retainer Type: SIM7050.

#### 3.0 PRODUCT SHAPE, DIMENSIONS AND MATERIAL.

Please refer to drawings.

#### 4.0 RATINGS.

Current rating ...... 0.5 Amp Max

Operating Temperature Range ..... -40°C to +85°C

Storage Temperature ..... -25°C to +85°C

Storage Humidity...... Relative Humidity: 45% ~ 75% R.H.

#### 5.0 TEST AND MEASUREMENT CONDITIONS.

Product is designed to meet electrical, mechanical and environmental performance requirements. specified in Paragraph 6.0. All tests are performed at ambient environmental conditions unless otherwise specified.

#### 6.0 PERFORMANCE.

| Item                   | Test Condition   | Requirement   |
|------------------------|--|---|
| Examination of Product | Visual, dimensional and functional inspection as per quality plan. | Product shall meet requirements of product drawing and specification. |



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#### 6.1 Electrical Performance.

| Item                  | Test Condition  | Requirement   |
|-----------------------|---|---|
| Contact Resistance    | Measure and record contact resistance of mated connector using test current of 10mA max and 20 mV open circuit voltage in accordance with EIA-364-23.         | 100 mΩ max initial  |
| Insulation Resistance | Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector.  In accordance with EIA-364-21. | 1000 MΩ minimum<br>@500V DC                                       |
| Dielectric Strength   | Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector.  In accordance with EIA-364-20. | Connector must withstand test potential of 500-V AC for 1 minute. |

## 6.2 Mechanical Performance.

| Item  | Test Condition  | Requirement   |
|---|---|---|
| Durability  | Insert & remove SIM card for 5000cycles. In accordance with EIA-364-09.   | Contact Resistance: 100mΩ max.  |
| Frequency: 10~100Hz, 0.0132 g²/Hz; Frequency: 100~500Hz, -3db/Oct Applied for 1 hour in each 3 mutually perpendicular axes (IEC60068-2-64-Fh) |   | No electrical discontinuity greater than 1 μsec (s) shall occur. Contact resistance:100mΩ max.                    |
| Mechanical Shock  | Pulse shape = half sine Peak acceleration = 490m/s² (50G) Duration of pulse = 11ms Apply 3 successive shocks in each direction along the 3 mutually perpendicular axes. (IEC-60068-2-27-EA) | No electrical discontinuity greater than 1 µsec. shall occur. No damage to product. Contact resistance:100mΩ max. |



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## 6.3 Environmental Performance and Others.

| Item   | Test Condition   | Requirement   |
|--|--|---|
| Thermal Shock  | 5 cycles at Ta= -55°C for 0.5 hours, then change temp = 25°C MAX 5min, then, T <sub>b</sub> = +85°C for 0.5hour, then cool to ambient. Recovery: 2hours at ambient atmosphere.  EIA-364-32 | No damage, Contact Resistance<br>(Low Level) (Final) 100mΩ max  |
| Humidity Test  | The card shall be mated and exposed to the condition of +40±2 @ 90~95% humidity for 96 hours Recovery time 1~2 hours. In accordance with EIA-364-31.                                       | No damage, Contact Resistance (Low Level) (Final) $100m\Omega$ max. Dielectric Strength should be OK, Insulation Resistance should be $100M\Omega$ min. |
| Salt Water Spray   | 5±1% salt concentration 24 hours 35±2°C<br>EIA-364-26  | No rusty cracks found. Contact<br>Resistance (Low Level) (Final)<br>100mΩ max   |
| Temperature Life (High)  | Subject product to 85±2°C for 96 hours continuously. EIA-364-17.   | Contact resistance: 100mΩ max   |
| Temperature Rise   | Mate card and measure the temperature rise of contact, when rated current is passed.  In accordance with EIA-364-70 Method 1.  | 30°C Max  |
| Solderability  | Dip solders tails into molten solder,<br>held at a temperature of 250±5°C<br>up to 0.5mm from the tip of the tails<br>for 3±0.5 seconds.   | Contact solder pad has a min.<br>95% solder coverage  |
| Resistance to Hand Soldering Heat Solder Temperature: 350 °C |  | No damage   |
| Resistance to Reflow<br>Soldering Heat.  | Mount connector, place in reflow oven and expose to the temperature profile shown in fig 1.0   | No evidence of physical damage or abnormalities adversely affecting performance.  |



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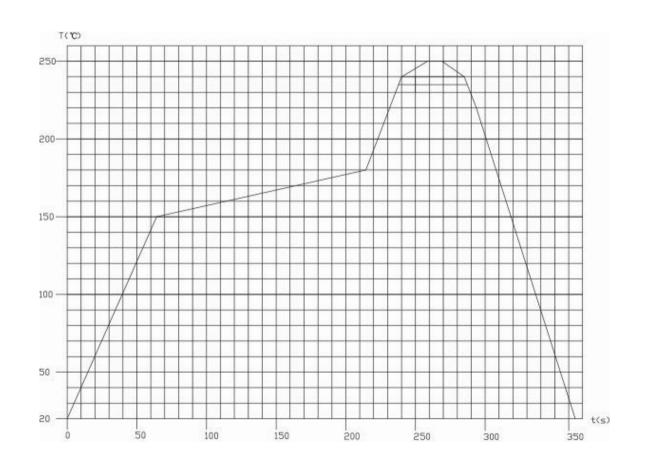
### 6.4 REFLOW SOLDERING PROFILE

Pb-free reflow profile requirements

| Parameter                                  | Specification   |
|--|-----------------|
| Average temperature gradient in preheating | 2.5°C/s         |
| Preheating Temperature                     | 150°C~200°C     |
| Soak time                                  | 120-180 seconds |
| Time above 217°C                           | 40~120 seconds  |
| Peak temperature in reflow                 | 235°C~250°C     |
| Time at peak temperature                   | 10-50 seconds   |
| Temperature gradient in cooling            | Max -5°C/s      |

Temperature profile for lead-free soldering

Temperature measured on solderable termination





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### 7.0 PRODUCT QUALIFICATION AND TEST SEQUENCE

| Test Item                              |     |     |     |     | G   | roup |     |     |     |     |   |
|--|-----|-----|-----|-----|-----|------|-----|-----|-----|-----|---|
|  | Α   | В   | С   | D   | E   | F    | G   | Н   | I   | J   |   |
| Examination of Product                 | 1,5 | 1,3 | 1,6 | 1,5 | 1,8 | 1,3  | 1,3 | 1,5 | 1,5 | 1,3 |   |
| Contact Resistance                     | 2,4 |     | 2,5 | 2,4 | 2,6 |      |     | 2,4 | 2,4 |     |   |
| Insulation Resistance                  |     |     |     |     | 3,7 |      |     |     |     |     |   |
| Dielectric Withstanding<br>Voltage     |     |     |     |     | 4   |      |     |     |     |     |   |
| Durability                             | 3   |     |     |     |     |      |     |     |     |     | Ī |
| Temperature Rise                       |     | 2   |     |     |     |      |     |     |     |     |   |
| Vibration                              |     |     | 4   |     |     |      |     |     |     |     |   |
| Mechanical Shock                       |     |     | 3   |     |     |      |     |     |     |     | Ī |
| Thermal Shock                          |     |     |     | 3   |     |      |     |     |     |     | T |
| Humidity                               |     |     |     |     | 5   |      |     |     |     |     | T |
| Solderability                          |     |     |     |     |     | 2    |     |     |     |     | Ī |
| Resistance to reflow<br>Soldering Heat |     |     |     |     |     |      | 2   |     |     |     |   |
| Salt Spray                             |     |     |     |     |     |      |     | 3   |     |     | T |
| High Temperature                       |     |     |     |     |     |      |     |     | 3   |     | T |
| Resistance to hand<br>Soldering Heat   |     |     |     |     |     |      |     |     |     | 2   |   |



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### Revision details:-

| Revision | Information            | Page | Release Date |  |
|----------|------------------------|------|--------------|--|
| Α        | Specification Released | -    | 22/12/2014   |  |
|          |                        |      |              |  |
|          |                        |      |              |  |

